~~surface of a projection on the first surface to make the layer to layer connection of said multilayer circuit;~~ for electrically conducting said conductive layer of one of said circuit layers to said conductive layer of another one of said circuit layers, wherein when said multilayer circuit is on the first surface, said conductive layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers by said second conductive layer on the side surface of said projection as the second surface; and

when said multilayer circuit is on the level surface of the second surface of said substrate, said conductive layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers by said second conductive layer on the second surface extending from the end of the first surface at an obtuse angle.

~~wherein the first surface is a top surface of said substrate, and the second surface further includes a side surface of said substrate, and~~

~~wherein the required angle between the first and second surfaces is an obtuse angle.~~

8. (Currently Amended) A multilayer circuit board comprising:

a substrate having a first surface and a projection formed on the first surface, a side surface of said projection extending at an obtuse angle relative to the first surface;

a pair of multilayer circuits formed on the first surface at both sides of said projection, each of said multilayer circuits composed of a plurality of

circuit layers, each of which is provided with a conductive-metal layer having a required circuit pattern and an insulation layer formed on said conductive-metal layer by film formation; and

a second conductive-metal layer successively formed on side and top surfaces of said projection,

wherein said conductive-metal layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers by said second conductive-metal layer on the side surface of said projection, and simultaneously one of the pair of multilayer circuits is electrically connected to the other one by said second conductive-metal layer on the side and top surfaces of said projection, .

~~wherein an angle between the side surface of said projection and the first surface is an obtuse angle.~~

9. (Previously Presented) The multilayer circuit board as set forth in claim 8, wherein said multilayer circuit has an aperture, through which a part of the first surface is exposed, and an electronic device is mounted in a concave formed in the exposed first surface, and an electrical connection between said multilayer circuit and said electronic device is made by a third conductive-metal layer formed on an inner surface of said concave.

10. (Previously Presented) The multilayer circuit board as set forth in claim 8, wherein said second conductive-metal layer is a plurality of second conductive layers to obtain plural layer-to-layer connections of said multilayer circuit, and each of second